PMEG3005CT

500 mA low VF dual Schottky barrier rectifier

3 April 2024 **Product data sheet**

1. General description

Planar Schottky barrier rectifier in common cathode configuration with an integrated guard ring for stress protection, encapsulated in a SOT23 small Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 0.5$ A
- Reverse voltage: $V_R \leq 30$ V
- Small SMD plastic package
- Low forward voltage
- AEC-Q101 qualified

3. Applications

- Low voltage rectification
- Reverse polarity protection
- High efficiency DC-to-DC conversion
- High-speed switching
- Switch Mode Power Supply (SMPS)
- Low power consumption applications

4. Quick reference data

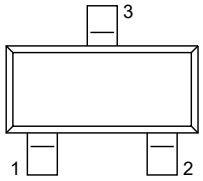
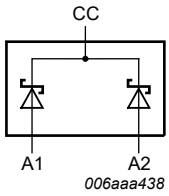
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per diode							
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20$ kHz; square wave; $T_{amb} \leq 95$ °C	[1]	-	-	0.5	A
		$\delta = 0.5$; $f = 20$ kHz; square wave; $T_{sp} \leq 130$ °C		-	-	0.5	A
V_R	reverse voltage	$T_j = 25$ °C		-	-	30	V
V_F	forward voltage	$I_F = 0.5$ A; $T_j = 25$ °C		-	375	430	mV
I_R	reverse current	$V_R = 30$ V; $T_j = 25$ °C		-	40	150	µA

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3, standard footprint.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode (diode 1)	 SOT23	
2	A	anode (diode 2)		
3	CC	common cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG3005CT	SOT23	plastic, surface-mounted package; 3 terminals; 1.9 mm pitch; 2.9 mm x 1.3 mm x 1 mm body	SOT23

7. Marking

Table 4. Marking codes

Type number	Marking code[1]
PMEG3005CT	P9%

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per diode						
V_R	reverse voltage	T_j = 25 °C		-	30	V
$I_{F(AV)}$	average forward current	δ = 0.5; f = 20 kHz; square wave; T_{amb} ≤ 95 °C	[1]	-	0.5	A
		δ = 0.5; f = 20 kHz; square wave; T_{sp} ≤ 130 °C		-	0.5	A
I_{FRM}	repetitive peak forward current	t_p ≤ 1 ms; δ ≤ 0.25		-	3.9	A
I_{FSM}	non-repetitive peak forward current	t_p = 8 ms; square wave; $T_{j(init)}$ = 25 °C		-	10	A
Per device; one diode loaded						
P_{tot}	total power dissipation	T_{amb} ≤ 25 °C	[2]	-	330	mW
			[3]	-	400	mW
			[1]	-	460	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

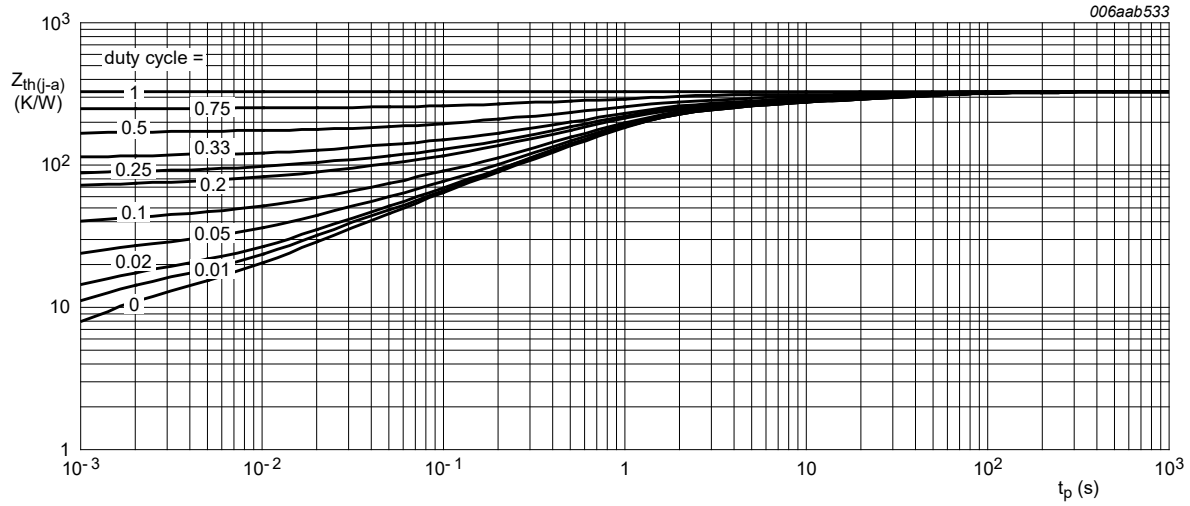
[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3, standard footprint.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.

9. Thermal characteristics

Table 6. Thermal characteristics

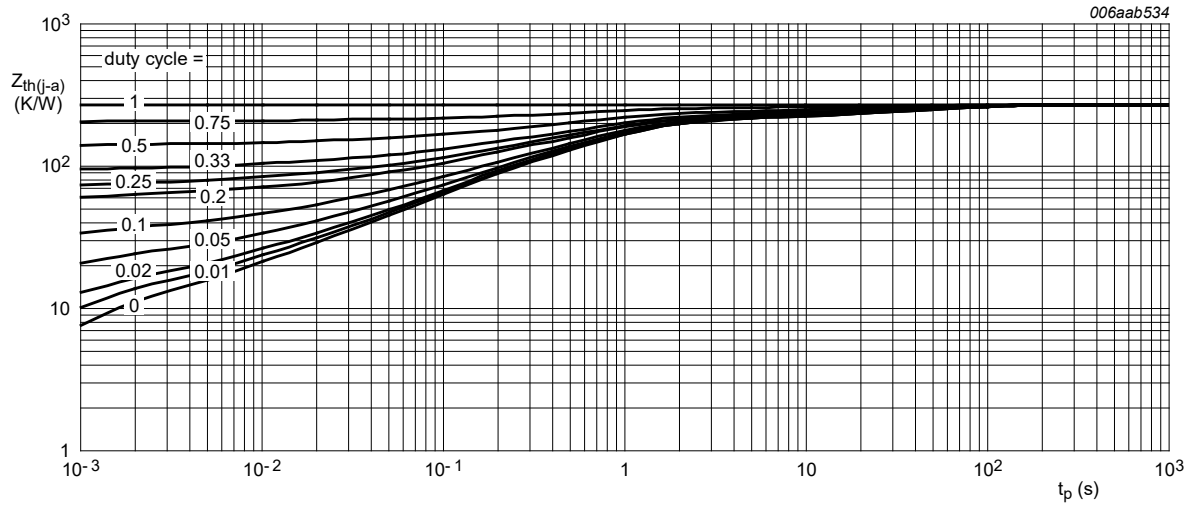
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	375	K/W
			[1] [3]	-	-	310	K/W
			[1] [4]	-	-	270	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	60	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.
[4] Device mounted on a ceramic PCB Al_2O_3, standard footprint.
[5] Soldering point of cathode tab.



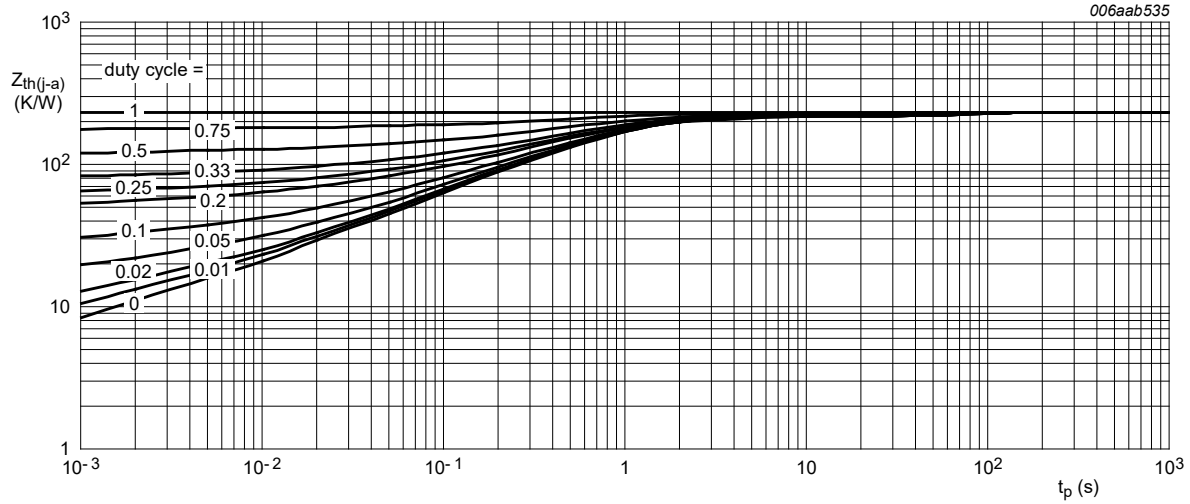
FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm^2

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



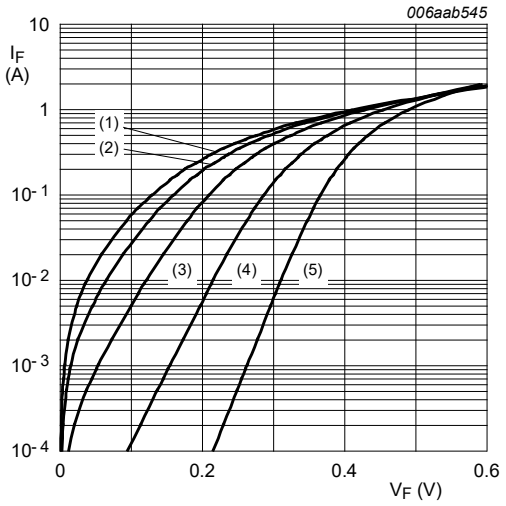
Ceramic PCB, Al_2O_3, standard footprint

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

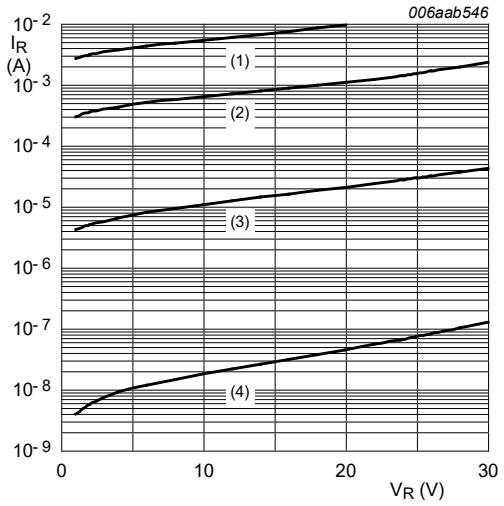
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per diode							
V_F	forward voltage	I_F = 0.1 mA; T_j = 25 °C		-	95	130	mV
		I_F = 1 mA; T_j = 25 °C		-	155	200	mV
		I_F = 10 mA; T_j = 25 °C		-	215	250	mV
		I_F = 100 mA; T_j = 25 °C		-	290	340	mV
		I_F = 0.5 A; T_j = 25 °C		-	375	430	mV
I_R	reverse current	V_R = 10 V; T_j = 25 °C		-	10	30	µA
		V_R = 30 V; T_j = 25 °C		-	40	150	µA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz; T_j = 25 °C		-	55	70	pF
t_{rr}	reverse recovery time	I_F = 10 mA; I_R = 10 mA; $I_{R(meas)}$ = 1 mA; R_L = 100 Ω		-	17	-	ns



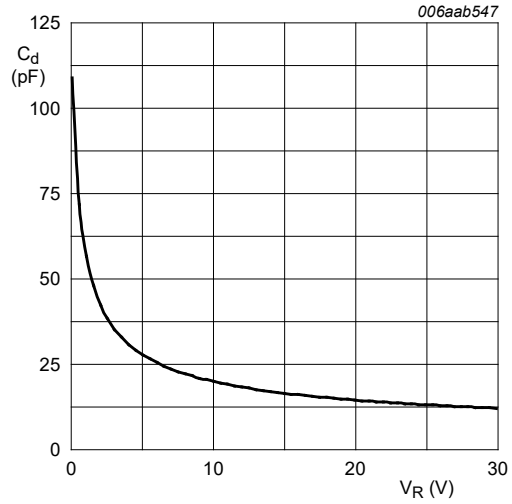
(1) T_j = 150 °C
(2) T_j = 125 °C
(3) T_j = 85 °C
(4) T_j = 25 °C
(5) T_j = -40 °C

Fig. 4. Forward current as a function of forward voltage; typical values



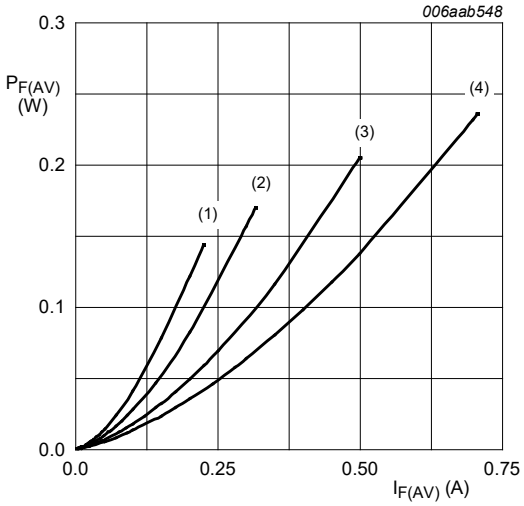
(1) T_j = 125 °C
(2) T_j = 85 °C
(3) T_j = 25 °C
(4) T_j = -40 °C

Fig. 5. Reverse current as a function of reverse voltage; typical values



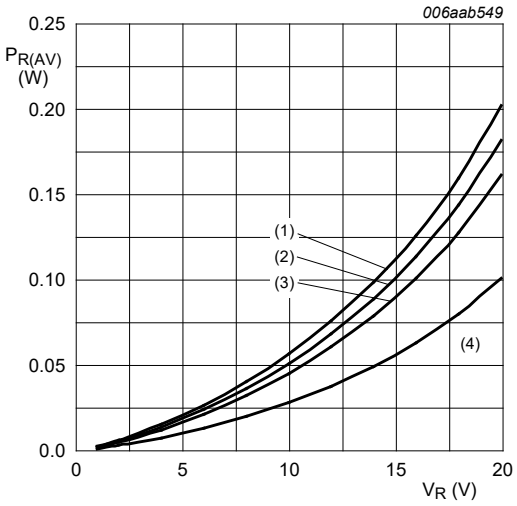
f = 1 MHz; Tamb = 25 °C

Fig. 6. Diode capacitance as a function of reverse voltage; typical values



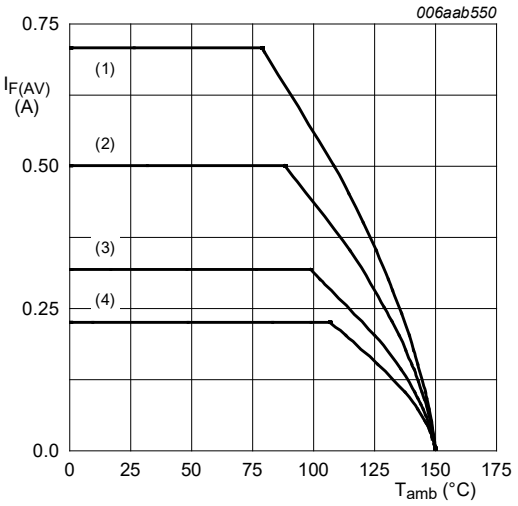
T_j = 150 °C
(1) δ = 0.1
(2) δ = 0.2
(3) δ = 0.5
(4) δ = 1

Fig. 7. Average forward power dissipation as a function of average forward current; typical values



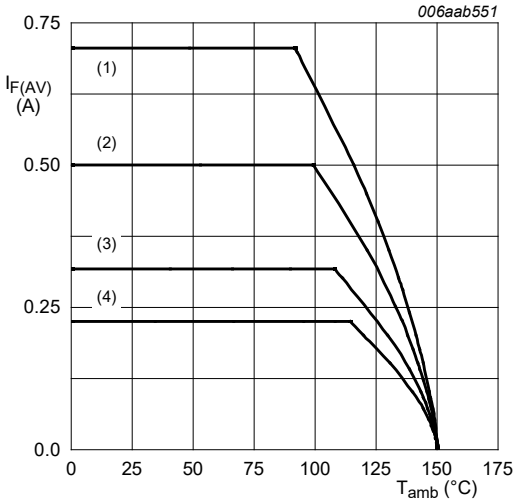
T_j = 125 °C
(1) δ =1
(2) δ = 0.9
(3) δ = 0.8
(4) δ = 0.5

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values



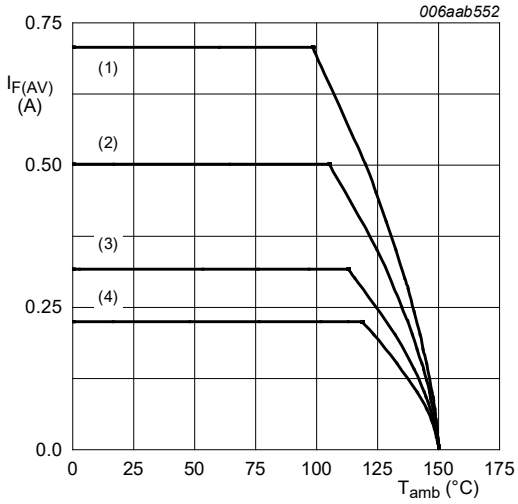
FR4 PCB, standard footprint
T_j = 150 °C
(1) δ = 1; DC
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



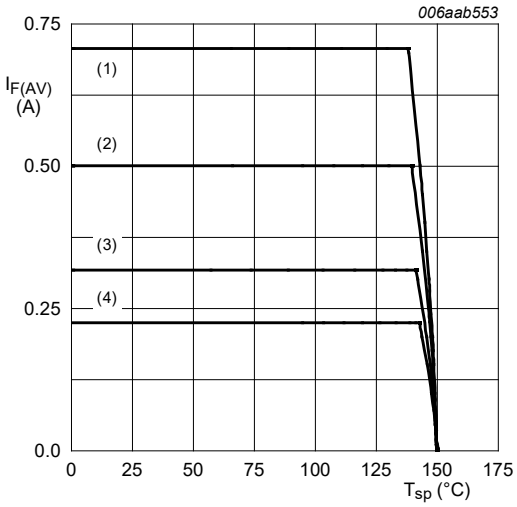
FR4 PCB, mounting pad for cathode 1 cm^2
T_j = 150 °C
(1) δ = 1; DC
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al_2O_3, standard footprint
T_j = 150 °C
(1) δ = 1; DC
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

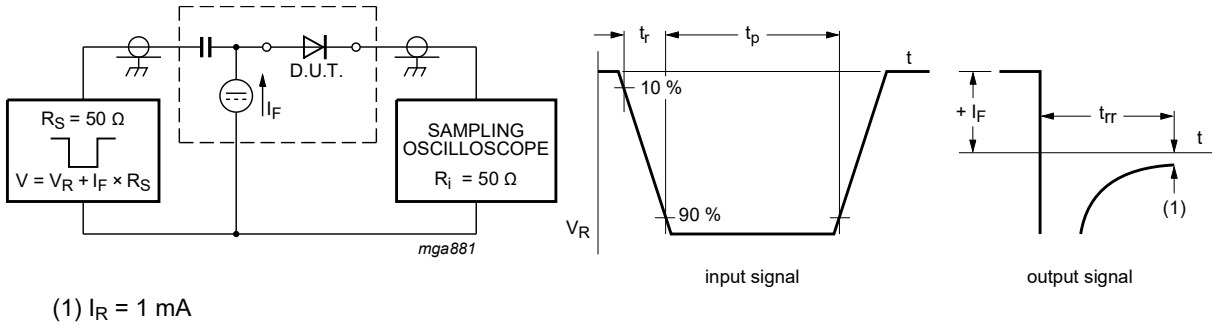
Fig. 11. Average forward current as a function of ambient temperature; typical values



T_j = 150 °C
(1) δ = 1; DC
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 12. Average forward current as a function of solder point temperature; typical values

11. Test information



(1) I_R = 1 mA

Fig. 13. Reverse recovery time: test circuit and waveforms

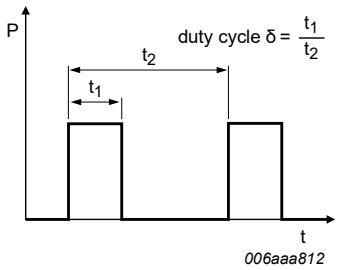


Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current

$I_{RMS} = I_{F(AV)}$ at DC

$I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

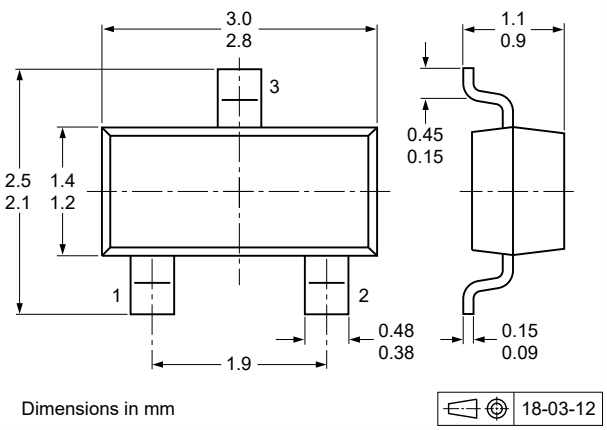


Fig. 15. Package outline SOT23

13. Soldering

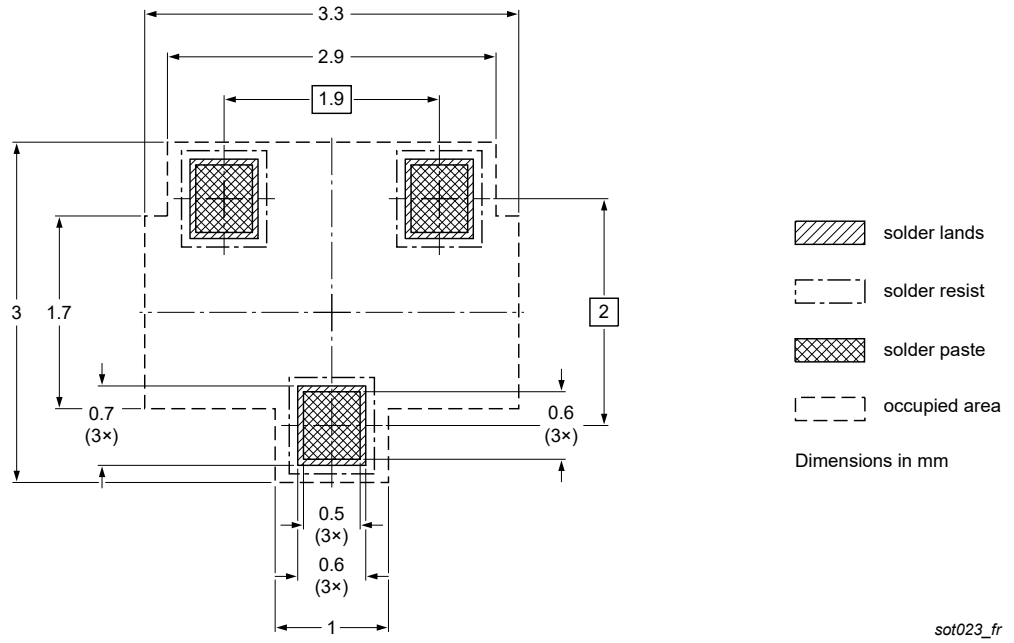


Fig. 16. Reflow soldering footprint for SOT23

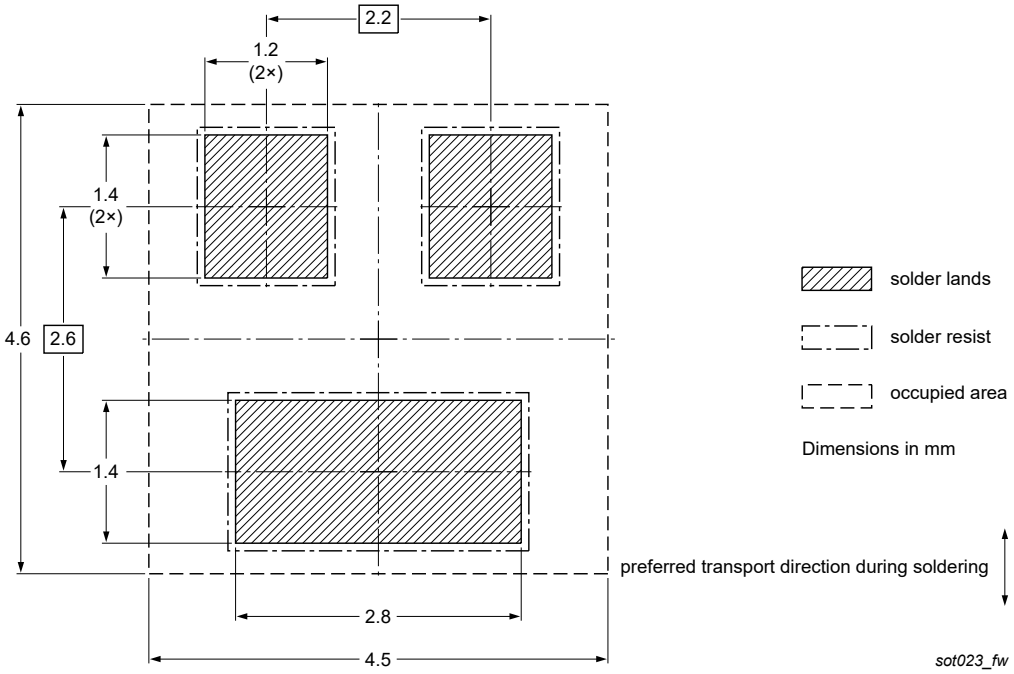


Fig. 17. Wave soldering footprint for SOT23

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG3005CT v.3	20240403	Product data sheet	-	PMEG3005CT v.2
Modifications:	• The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. • Legal texts have been adapted to the new company name where appropriate. • Section "Packing information" removed.			
PMEG3005CT v.2	20100920	Product data sheet	-	PMEG3005CT v.1
PMEG3005CT v.1	20090605	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 3 April 2024

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